

LNJ115W8RRA2

High Bright Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

- Green
- Soft Orange

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Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

- Green

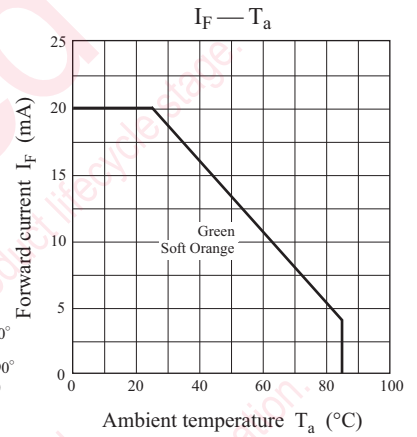
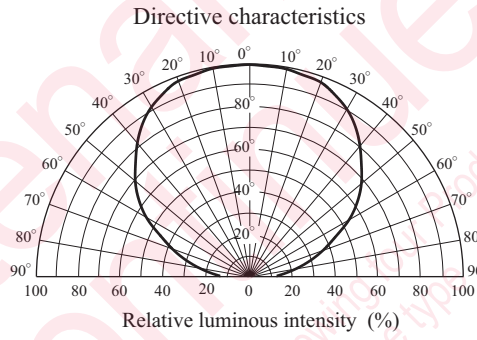
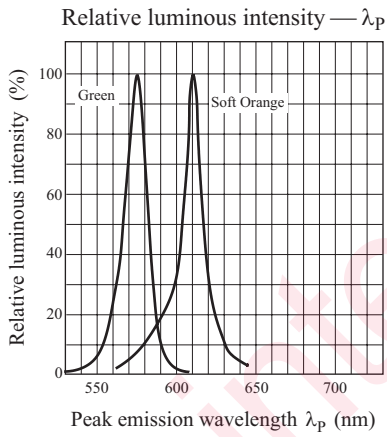
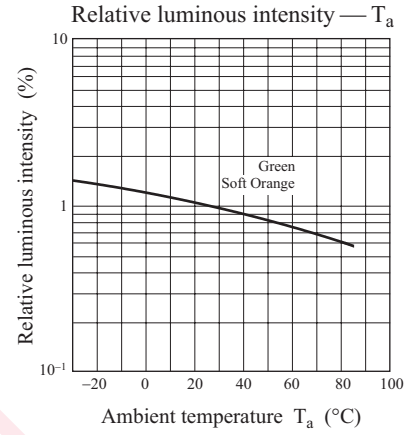
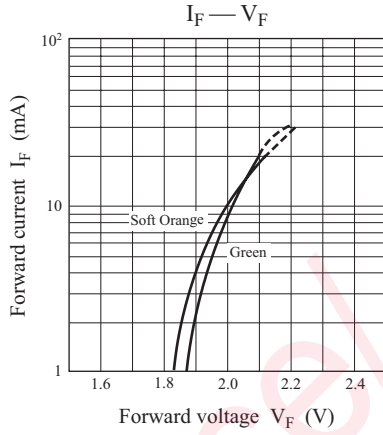
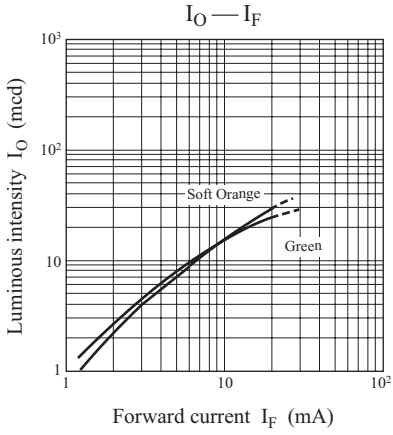
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10 \text{ mA}$	9	15		mcd
Reverse current	I_R	$V_R = 4 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10 \text{ mA}$		2.03	2.50	V
Peak emission wavelength	λ_p	$I_F = 10 \text{ mA}$		575		nm
Dominant emission wavelength	λ_d	$I_F = 10 \text{ mA}$		572		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		15		nm

Note) *: Measurement tolerance: $\pm 20\%$

- Soft Orange

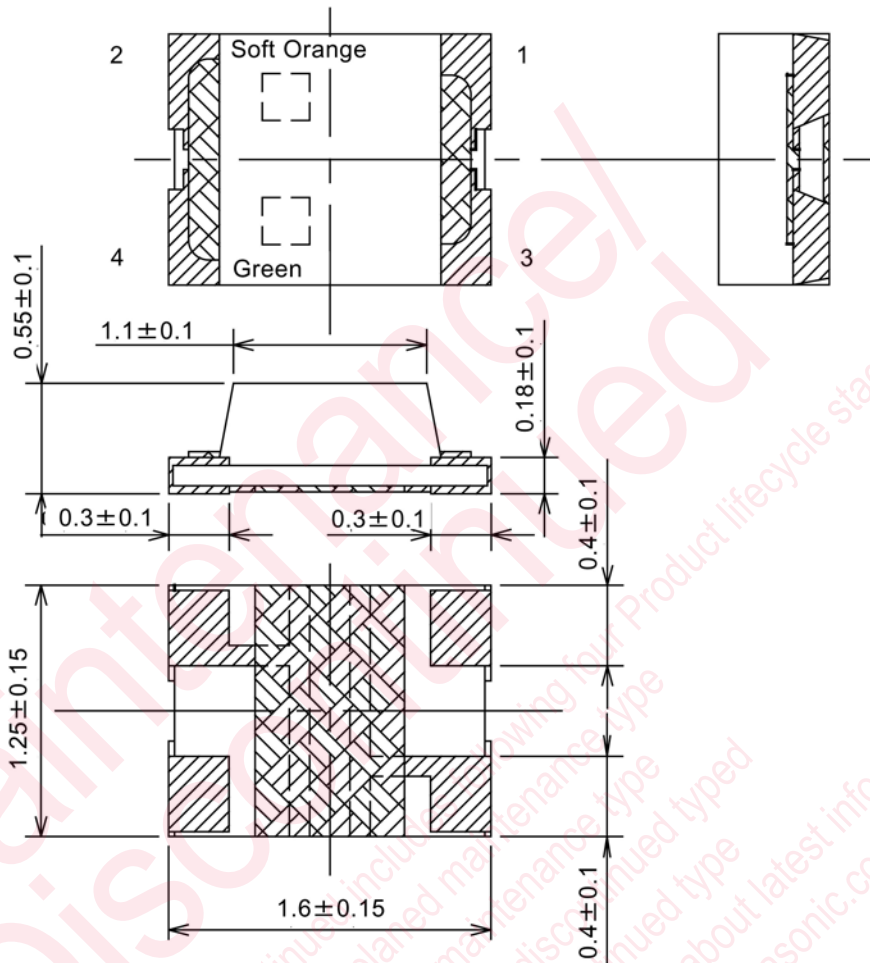
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10 \text{ mA}$	12	18		mcd
Reverse current	I_R	$V_R = 4 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10 \text{ mA}$		1.92	2.50	V
Peak emission wavelength	λ_p	$I_F = 10 \text{ mA}$		610		nm
Dominant emission wavelength	λ_d	$I_F = 10 \text{ mA}$		605		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		15		nm

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

KLTFTN4K1540



- Pin name
 1, 3: Anode
 2, 4: Cathode

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